

TOSHIBA PHOTO-INTERRUPTERS INFRARED LED + PHOTOTRANSISTOR

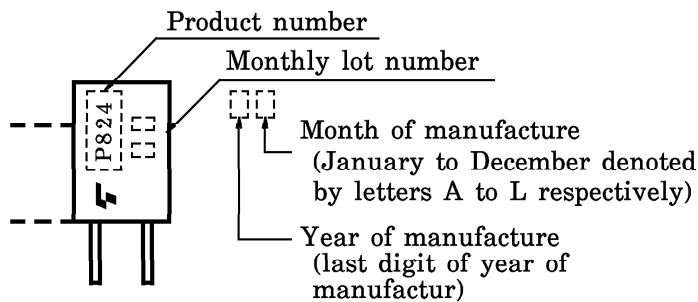
TLP824, TLP825

- VCRS, COMPACT DISC PLAYERS
- COPIERS, FAX MACHINES, PRINTERS
- VENDING MACHINES, TICKET MACHINES
- VARIOUS POSITION DETECTION SENSORS

The TLP824 and TLP825 photo-interrupters combine a GaAs infrared LED with a high-sensitivity Si photodarlington transistor.

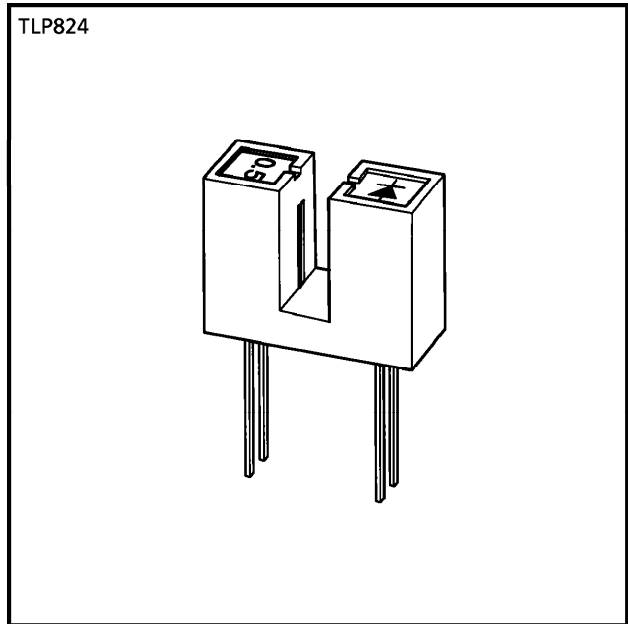
- Small package
- PWB direct mounting type : TLP824
- Side mounting type : TLP825
- Gap : 3 mm
- Resolution : Slit width = 0.5 mm
- High current transfer ratio : $I_C / I_F = 6\%$ (min) at $I_F = 10\text{ mA}$
- Detector impermeable to visible light
- Package material : Polycarbonate

MARKINGS

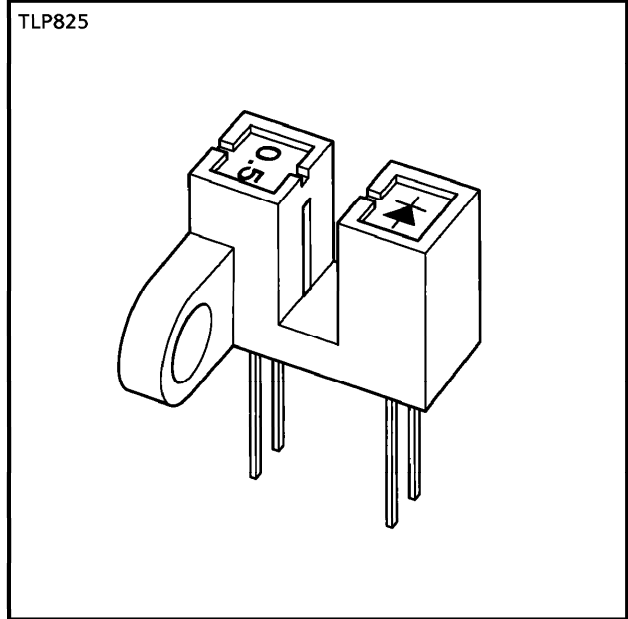


Letter color : Silver

ABBREVIATION	TYPE
P824	TLP824
P825	TLP825



TOSHIBA 11-13K1



TOSHIBA 11-13M1

Weight : 0.81 g (typ.)
0.82 g (typ.)

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC		SYMBOL	RATING	UNIT
LED	Forward Current	I _F	50	mA
	Forward Current Derating (Ta > 25°C)	ΔI _F /°C	-0.33	mA/°C
	Reverse Voltage	V _R	5	V
DETECTOR	Collector-Emitter Voltage	V _{CEO}	35	V
	Emitter-Collector Voltage	V _{ECO}	5	V
	Collector Power Dissipation	P _C	75	mW
	Collector Power Dissipation Derating (Ta > 25°C)	ΔP _C /°C	-1	mW/°C
	Collector Current	I _C	50	mA
	Operating Temperature Range	T _{opr}	-25~85	°C
	Storage Temperature Range	T _{stg}	-40~100	°C
Soldering Temperature (5 s.)		T _{sol}	260	°C

RECOMMENDED OPERATING CONDITIONS

CHARACTERISTIC	SYMBOL	Min	Typ.	Max	UNIT
Supply Voltage	V _{CC}	—	5	24	V
Forward Current	I _F	—	10	20	mA
Operating Temperature	T _{opr}	-10	—	75	°C

OPTICAL AND ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC		SYMBOL	TEST CONDITION	Min	Typ.	Max	UNIT
LED	Forward Voltage	V _F	I _F = 10 mA	1.00	1.15	1.30	V
	Reverse Current	I _R	V _R = 5 V	—	—	10	μA
	Peak Emission Wavelength	λ _P	I _F = 10 mA	—	940	—	nm
DETECTOR	Dark Current	I _D (I _{CEO})	V _{CE} = 24 V, I _F = 0	—	—	0.1	μA
	Peak Sensitivity Wavelength	λ _P		—	870	—	nm
COUPLED	Current Transfer Ratio	I _C / I _F	V _{CE} = 2 V, I _F = 10 mA	6	—	90	%
	Collector-Emitter Saturation Voltage	V _{CE} (sat)	I _F = 20 mA, I _C = 0.6 mA	—	0.1	0.4	V
	Rise Time	t _r	V _{CC} = 5 V, I _C = 1 mA, R _L = 1 kΩ	—	15	50	μs
	Fall Time	t _f		—	15	50	

PRECAUTIONS

The following points must be borne in mind.

1. Clean only the soldered part of the leads. Do not immerse the entire package in the cleaning solvent.
2. The package is made of polycarbonate. Polycarbonate is usually stable with acid, alcohol and aliphatic hydrocarbons, however, with petrochemicals (such as benzene, toluene and acetone), alkalis, aromatic hydrocarbons, or chloric hydrocarbons, polycarbonate may crack, swell or melt. Please take this into account when choosing a packaging material by referring to the table below.

<Chemicals which should not be used with polycarbonate>

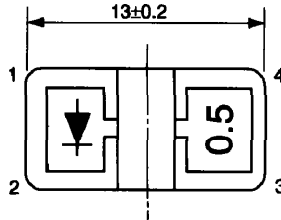
	PHENOMENON	CHEMICALS
A	Staining and slight deterioration	<ul style="list-style-type: none"> • Nitric acid (diluted), hydrogen peroxide, chlorine
B	Cracking, crazed or swelling	<ul style="list-style-type: none"> • Acetic acid (70% or more) • Gasoline • Methyl ethyl ketone, ethyl acetate, butyl acetate • Ethyl methacrylate, ethyl ether, MEK • Acetone, m-amino alcohol, carbon tetrachloride • Carbon disulfide, trichloroethylene, cresol • Thinners, oil of turpentine • Triethanolamine, TCP, TBP
C	Melting { } : Used as solvent	<ul style="list-style-type: none"> • Concentrated sulfuric acid • Benzene • Styrene, acrylonitrile, vinyl acetate • Ethylenediamine, diethylenediamine • {Chloroform, methyl chloride, tetrachloromethane, dioxane, } 1, 2-dichloroethane
D	Decomposition	<ul style="list-style-type: none"> • Ammonia water • Other alkalis

3. Mount the device on a level surface.
4. Screws should be tightened to a clamping torque of 0.59 N·m (on the TLP825).
5. Conversion efficiency falls over time due to the current which flows in the infrared LED. When designing a circuit, take into account this change in conversion efficiency over time. The ratio of fluctuation in conversion efficiency to fluctuation in infrared LED optical output is 1:1.

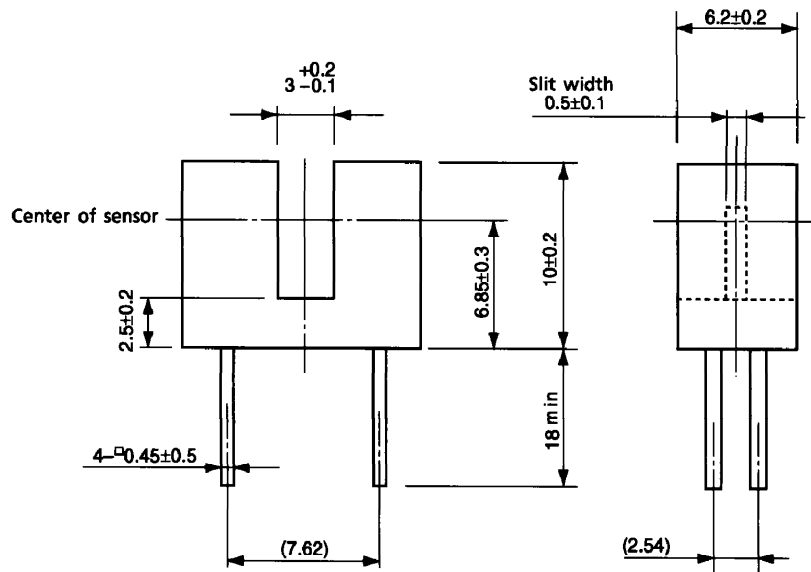
$$\frac{I_C / I_F (t)}{I_C / I_F (0)} = \frac{P_O (t)}{P_O (0)}$$

PACKAGE DIMENSIONS
11-13K1

Unit : mm



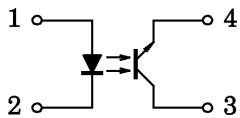
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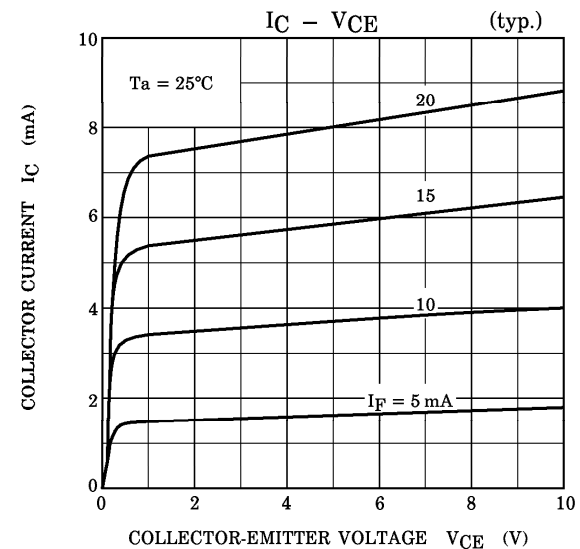
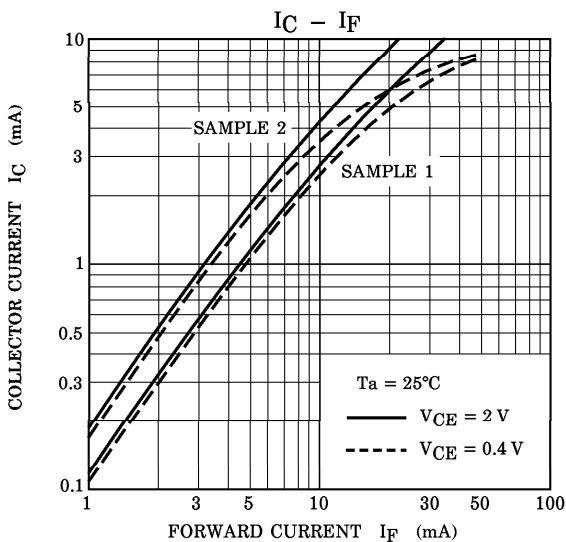
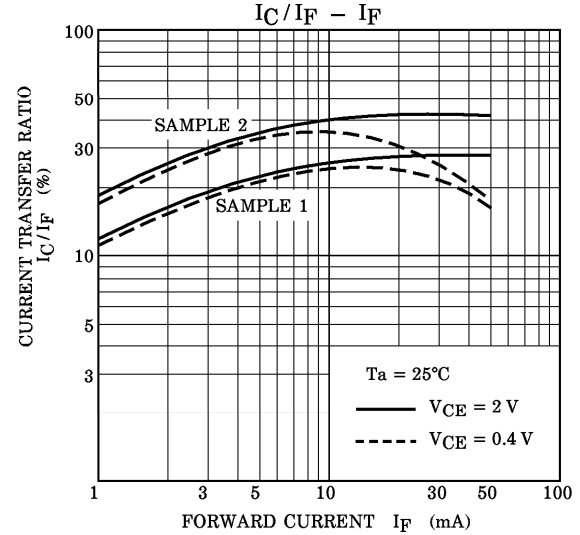
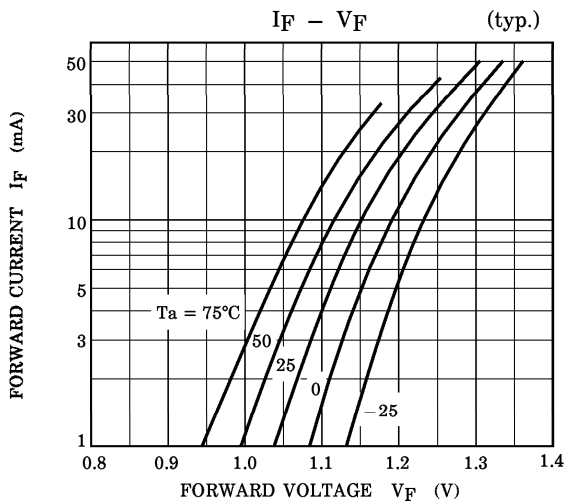
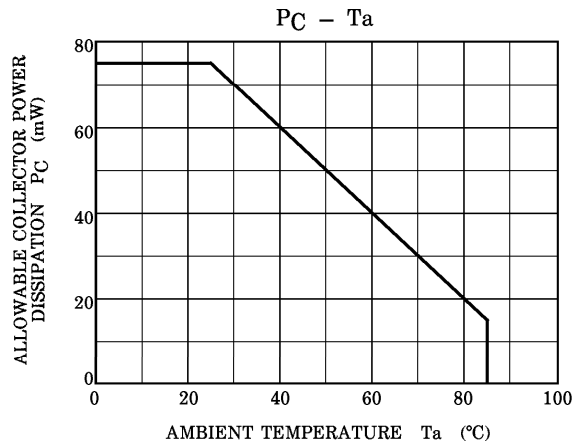
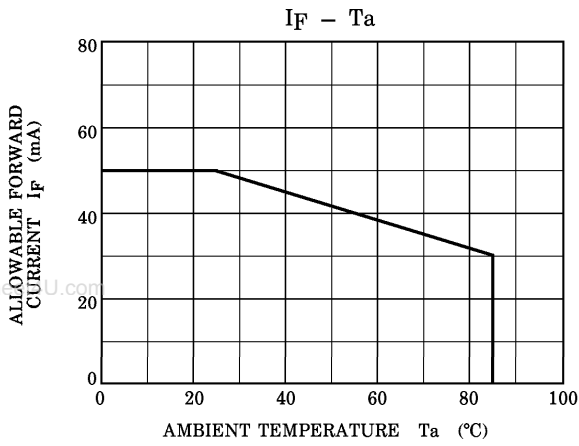
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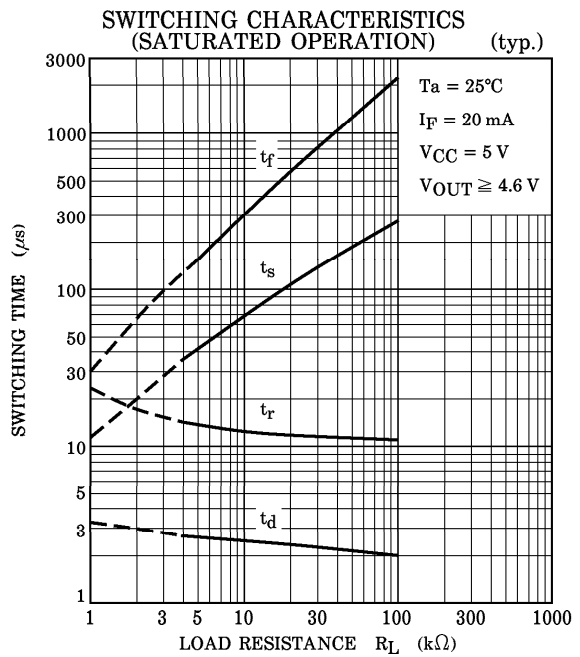
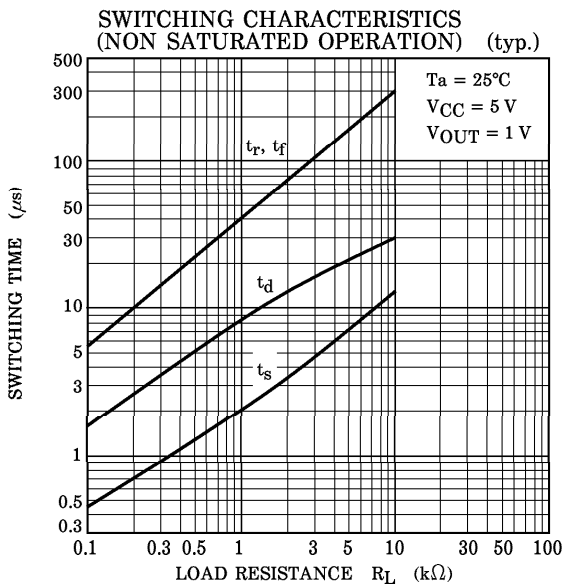
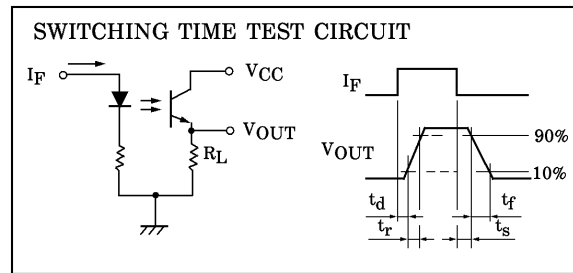
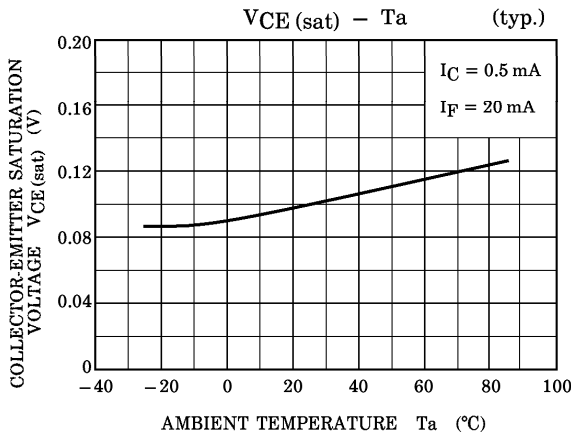
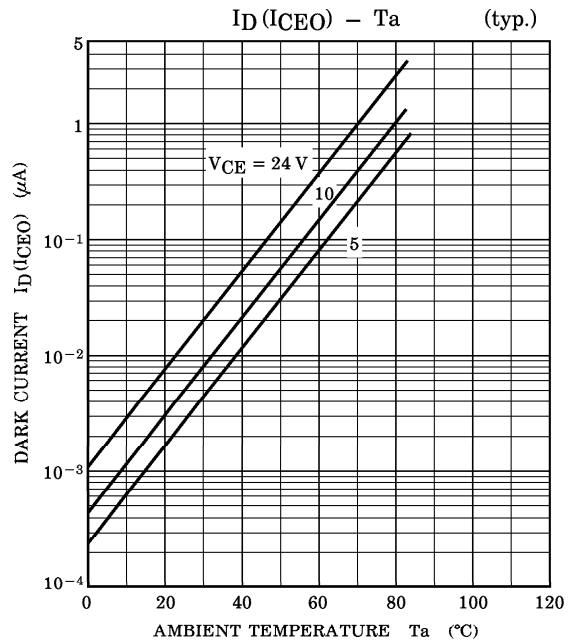
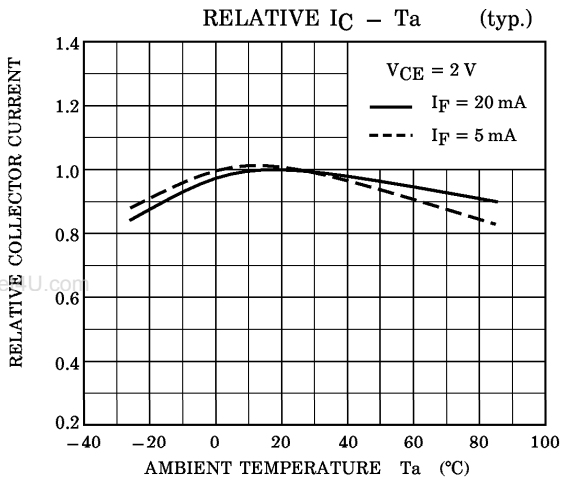
Weight : 0.81 g (typ.)

PIN CONNECTION

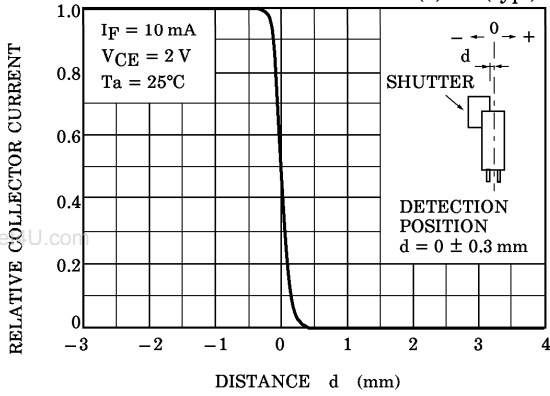


- 1. Anode
- 2. Cathode
- 3. Collector
- 4. Emitter

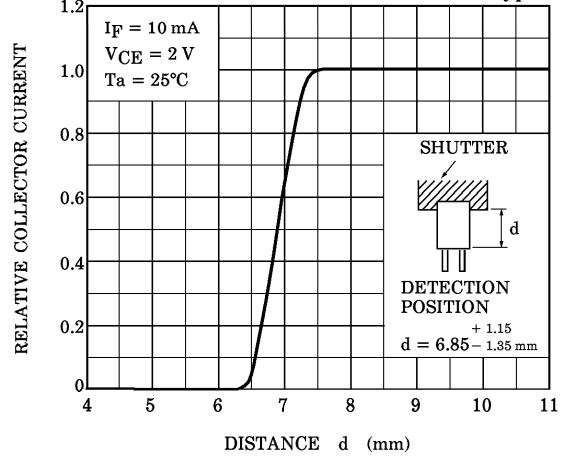




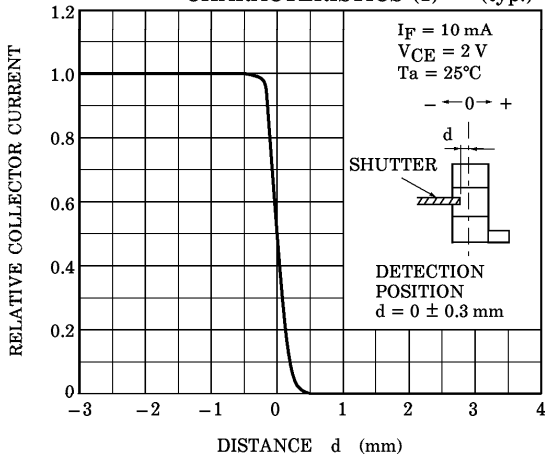
TLP824 DETECTION POSITION CHARACTERISTICS (1) (typ.)



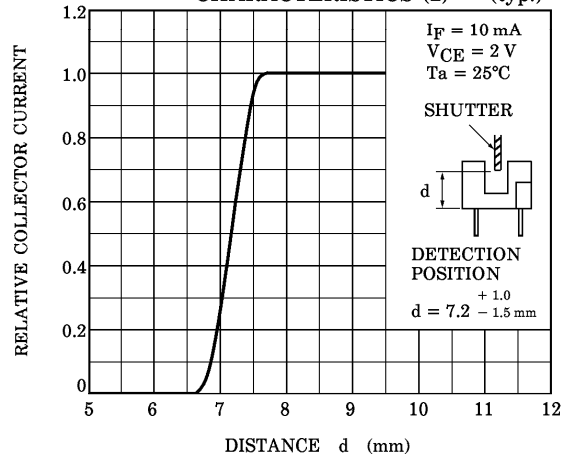
TLP824 DETECTION POSITION CHARACTERISTICS (2) (typ.)



TLP825 DETECTION POSITION CHARACTERISTICS (1) (typ.)



TLP825 DETECTION POSITION CHARACTERISTICS (2) (typ.)

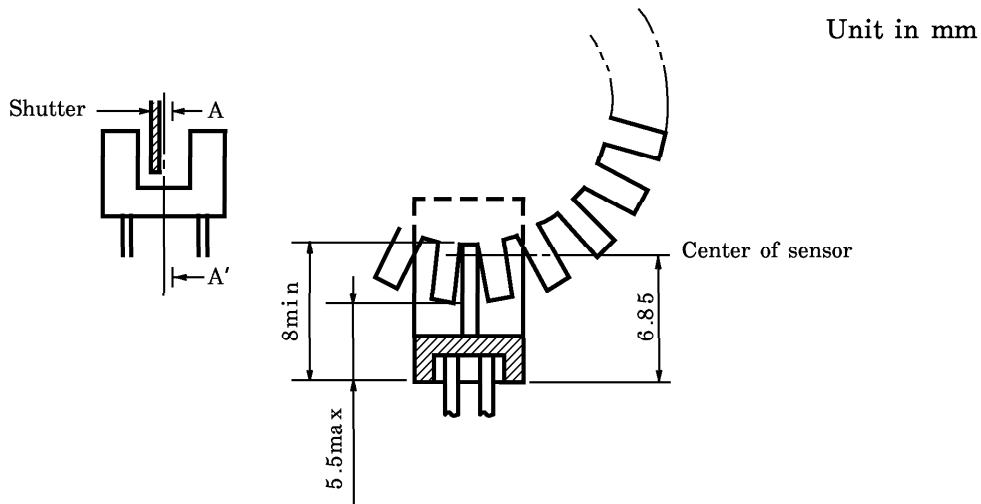


RELATIVE POSITIONING OF SHUTTER AND DEVICE

For normal operation position the shutter and the device as shown in the figure below. By considering the device's detection direction characteristic and switching time, determine the shutter slit width and pitch.

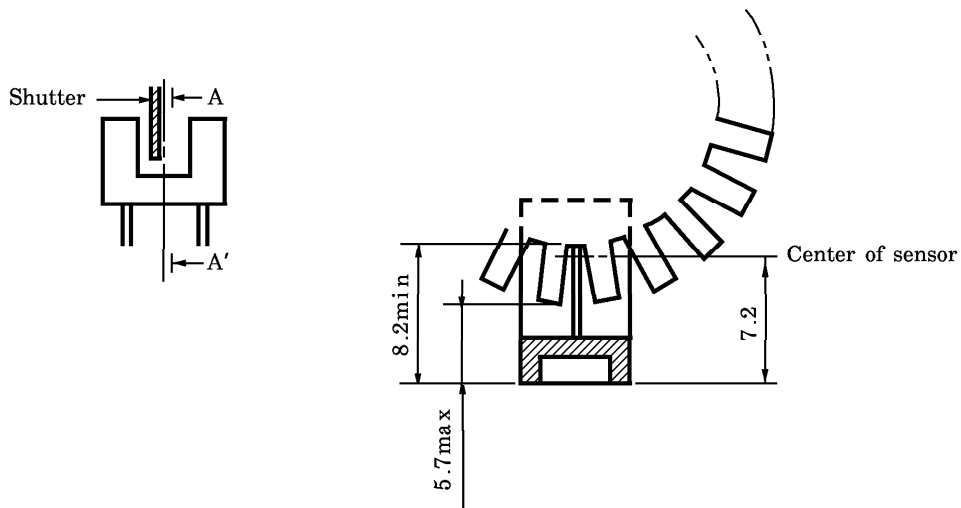
TLP824

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Cross section between A and A'

TLP825



Cross section between A and A'

RESTRICTIONS ON PRODUCT USE

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